ATDK Multilayer Ceramic Chip Capacitors

C1608X5R0J106M080AB



TDK item description C1608X5R0J106MT****

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C1608 [EIA 0603]	
Status	Production	



	Size	
Length(L)	1.60mm ±0.10mm	
Width(W)	0.80mm ±0.10mm	
Thickness(T)	0.80mm ±0.10mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	0.30mm Min.	
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering)	
	0.60mm to 0.80mm(Reflow Soldering)	
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering)	
	0.60mm to 0.80mm(Reflow Soldering)	
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering)	
	0.60mm to 0.80mm(Reflow Soldering)	

Electrical Characteristics		
Capacitance	10µF ±20%	
Rated Voltage	6.3VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	10ΜΩ	

Other		
Coldering Method	Wave (Flow)	
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	4000pcs	

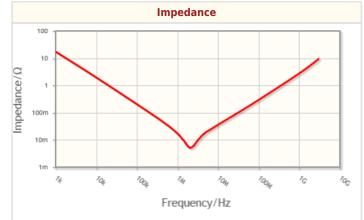
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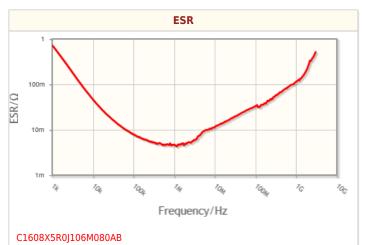
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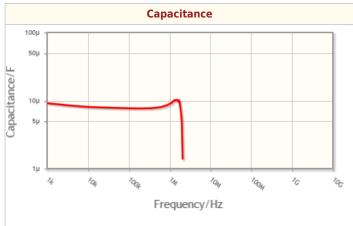


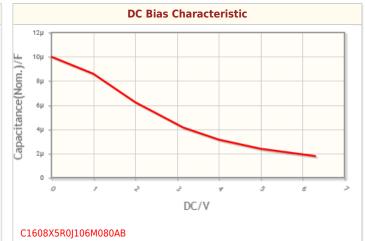


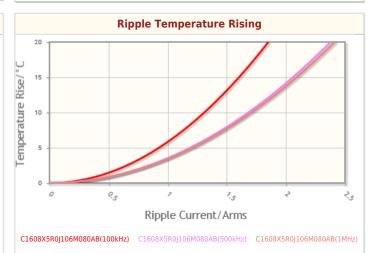


Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

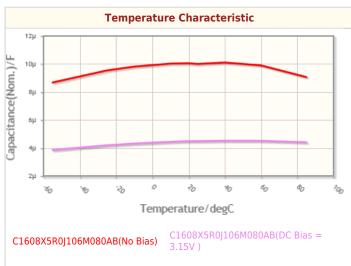








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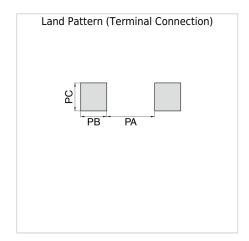
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Associated Images



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